

Title (en)

Circuit board device and a related electrical assembly

Title (de)

Leiterplattenvorrichtung und eine diesbezügliche elektrische Anordnung

Title (fr)

Dispositif à plaquettes et agencement électrique correspondant

Publication

EP 2634864 A3 20140521 (DE)

Application

EP 13153090 A 20130129

Priority

DE 102012203297 A 20120302

Abstract (en)

[origin: EP2634864A2] The device (2) has a strip conductor (8) that is extended along longitudinal direction (L) of substrate (6). An electrical contact element (14) electrically connected with printed circuit board (4) is provided in connector housing (12). The spring elements (18,20) provided on connector housing are connected with circuit board. The force (F1,F2) from the spring element made of metal or metal alloy is applied perpendicularly to printed circuit board in order to press the electrical contact element on strip conductor, if connector (10) is connected with printed circuit board.

IPC 8 full level

H01R 12/72 (2011.01); **H01R 12/85** (2011.01)

CPC (source: EP)

H01R 12/721 (2013.01); **H01R 12/85** (2013.01)

Citation (search report)

- [X] EP 0036933 A2 19811007 - ULRICH BOHDAN
- [A] EP 1009068 A1 20000614 - MOLEX INC [US]
- [A] US 3639888 A 19720201 - PITTMAN ROBERT B, et al
- [A] US 5295852 A 19940322 - RENN ROBERT M [US], et al
- [A] US 2007082542 A1 20070412 - NORRIS NATHAN J [US], et al

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

EP 2634864 A2 20130904; EP 2634864 A3 20140521; EP 2634864 B1 20161214; DE 102012203297 A1 20130905

DOCDB simple family (application)

EP 13153090 A 20130129; DE 102012203297 A 20120302